



Final Product Change Notification

201511018F01

Issue Date: 08-Dec-2015
Effective Date: 21-Mar-2016

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QUALITY

Management Summary

Change of bond wire material from Au to Cu for PBHV8115Z in SOT223 package.

Change Category

| | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu for product PBHV8115Z

Details of this Change

Scheduled change affects type PBHV8115Z in SOT223 package.

The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of change to copper wire as given by implementation date below. Gold wire remains qualified for supply security reasons only. Old product: Bond wire material is gold (Au).

Changed product: Bond wire material is copper (Cu) or gold (Au).

The design and materials of all other components will remain unchanged: die, die attach, mold compound and lead frame. Reliability qualification and full electrical characterizations have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

Aligning with world technology standards, NXP continues to introduce copper bonding wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Top side marking

Product can be identified by different date code format on package surface: Product with gold (Au) wire has a 2-digit date code.

Product with copper (Cu) wire will have a 3-digit date code.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 21-Mar-2016

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: view online

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 07-Jan-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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Changed Orderable Part#

PBHV8115Z,115

